

MATERIALS AND FINISHES:

BODY: ZINC ALLOY
PLATED NICKEL

CENTER CONTACT: PHOSPHOR BRONZE
PLATED GOLD

INSULATOR: POLYPROPYLENE (94V-2)

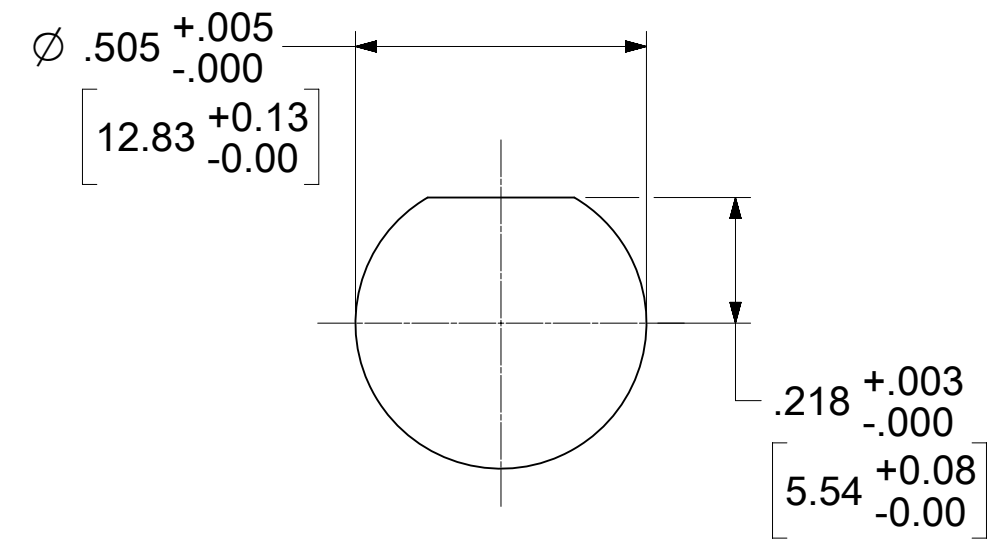
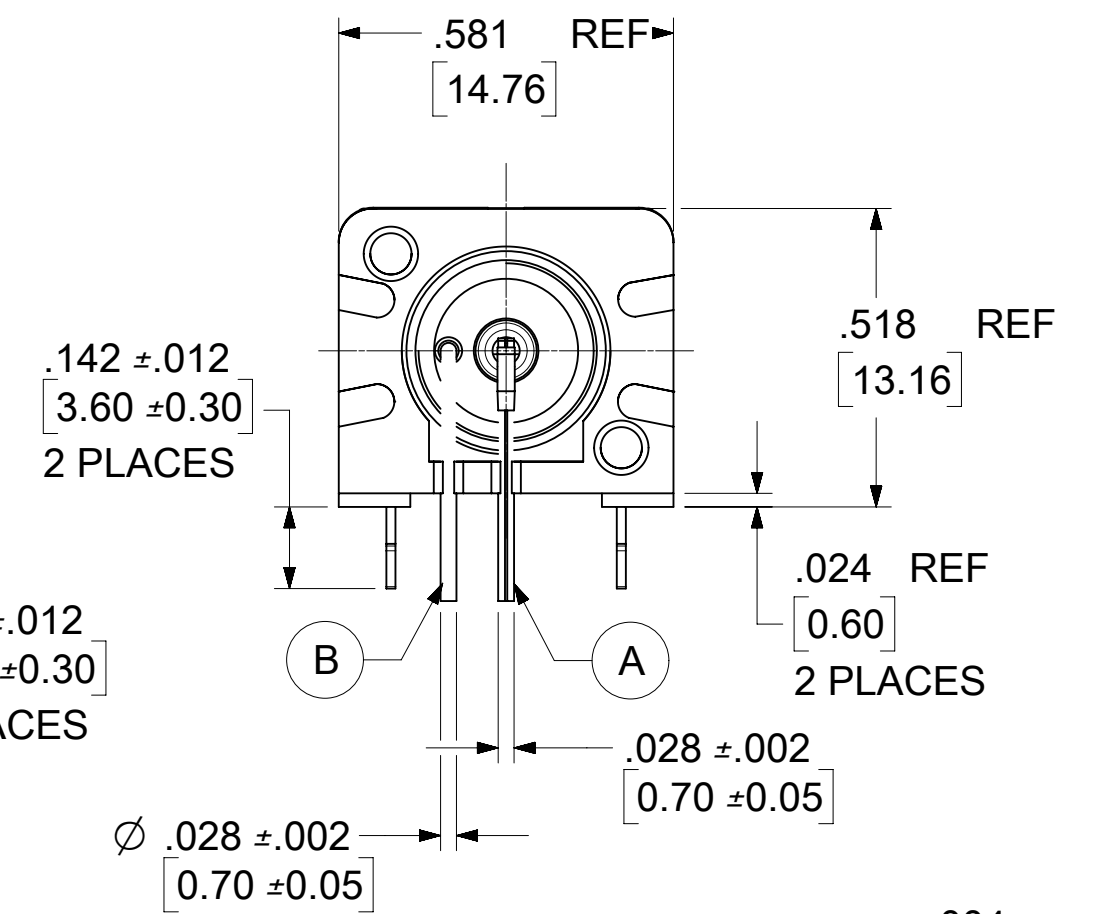
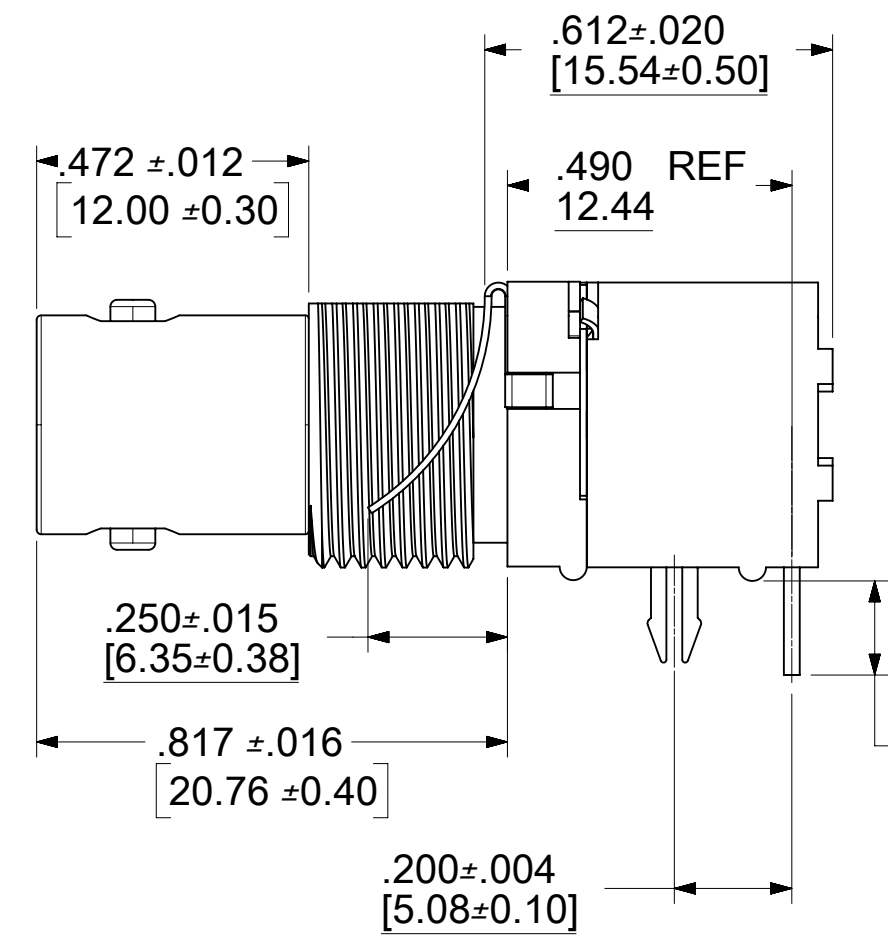
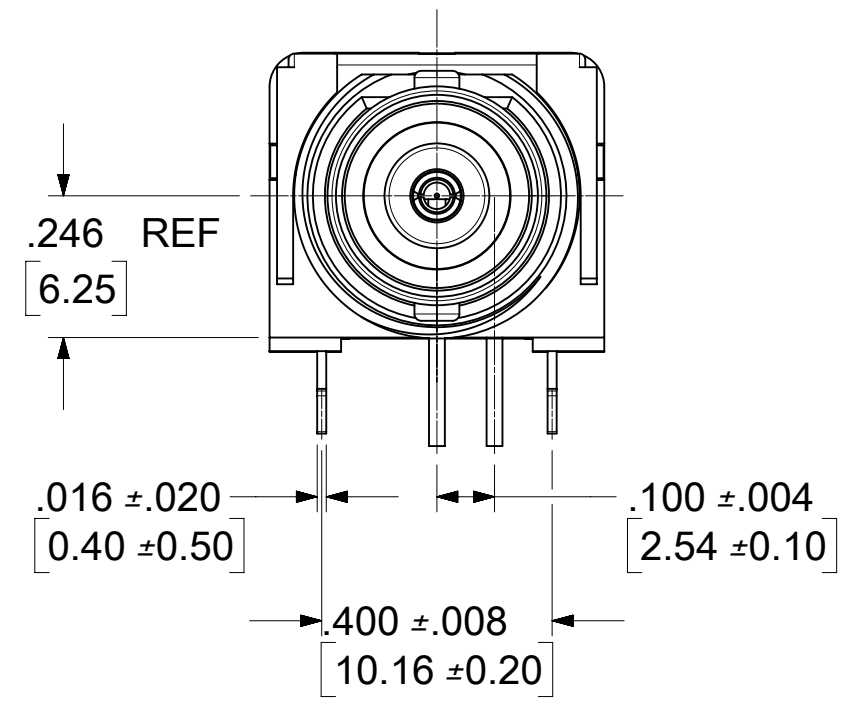
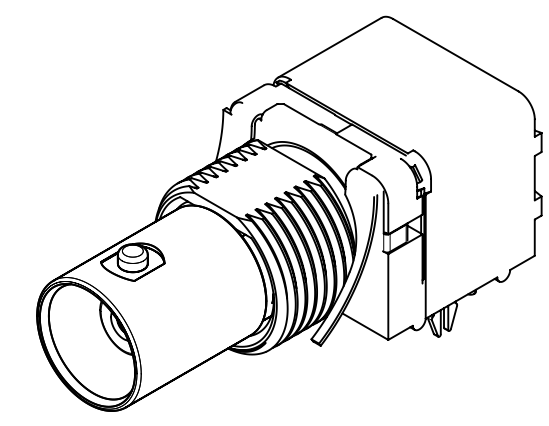
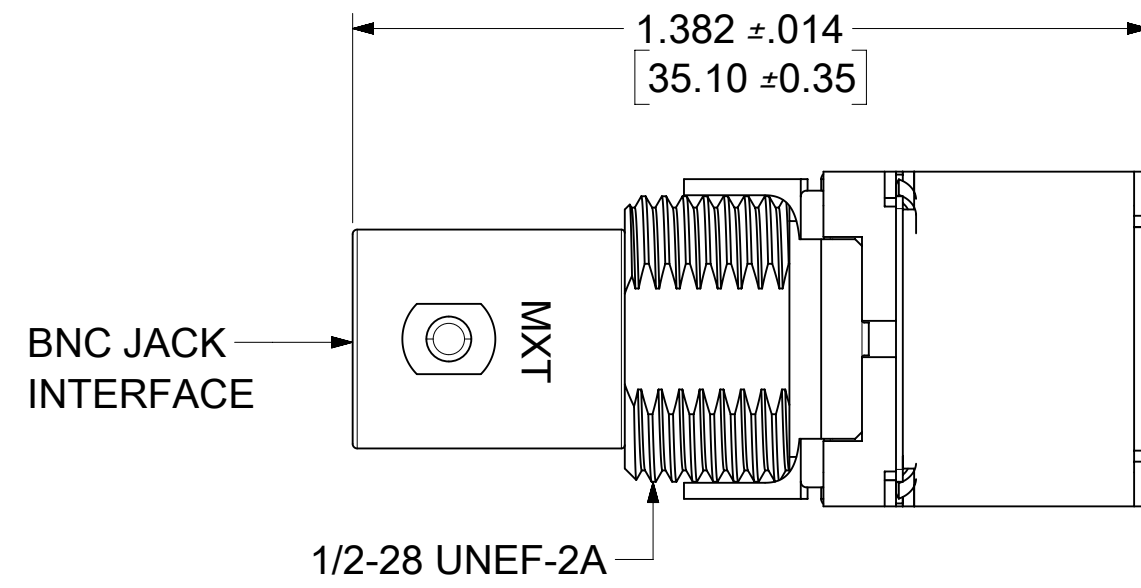
HOUSING: PBT BLACK

SOLDER TAIL: COPPER OVER STEEL WIRE
PLATED TIN

FRONT CLIP: PHOSPHOR BRONZE
PLATED NICKEL

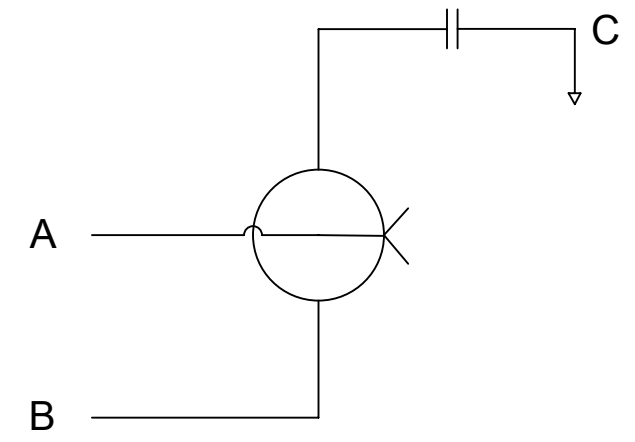
MULTILAYER CHIP CAPACITOR: CERAMIC

BOARD CLIP: PHOSPHOR BRONZE
PLATED TIN

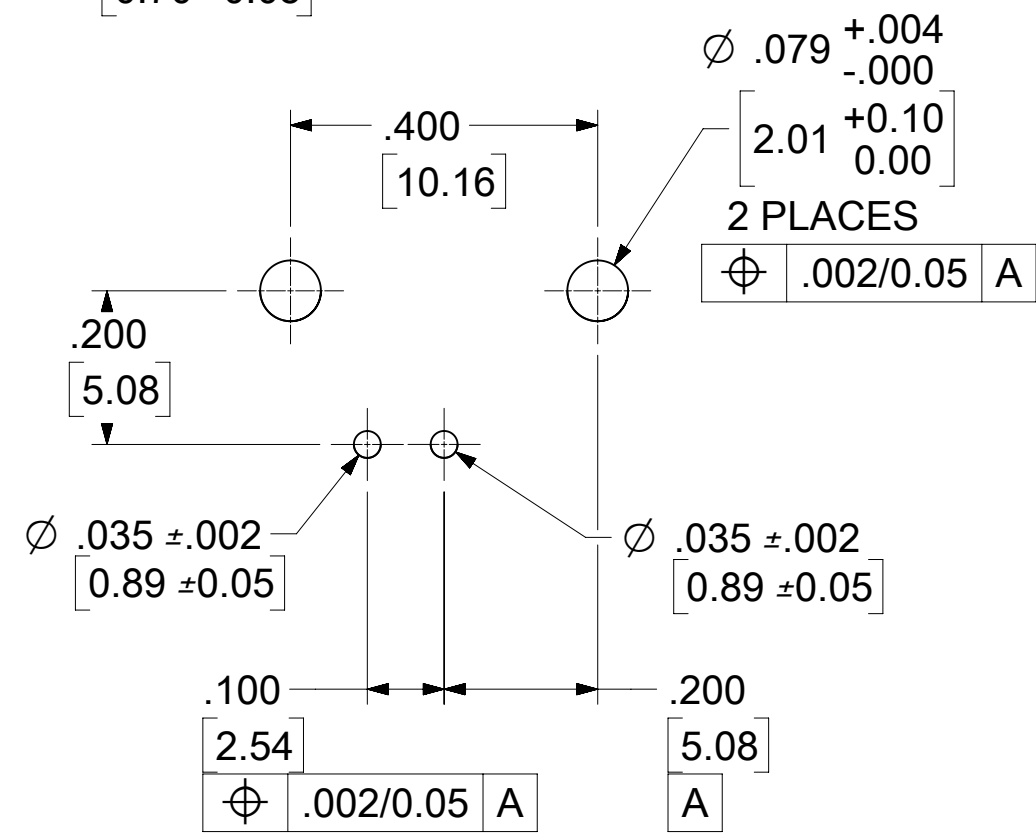


RECOMMENDED MOUNTING HOLE
RECOMMENDED MOUNTING TORQUE:
0.56 N-m(5.00 IN-LBS)
PANEL THICKNESS: .217 (5.5) MAX

1.5K / 2K VDC 9400pF ±20% X7R



SCHEMATIC



RECOMMENDED PCB LAYOUT

73171-3030	73100-0090 ONE PER BAG
73100-0090	TRAY
PART NO.	PACKAGING

ES-73599-0000	INTERFACE
PS-73598-0010	ELEC/MECH PERFORMANCE
SPECIFICATION	DESCRIPTION

F4	2019/3/27	REDRAW FOR MEASUREMENT .490/12.44 REF
F3	2019/2/27	ADD CHIP CAPACITOR DEFINITION PER EWR #12915-A
REV	DATE	DESCRIPTION

DOCUMENT STATUS	P1	RELEASE DATE	2019/03/27	08:37:19
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DIMENSION UNITS	SCALE	CURRENT REV	DESC:
HYBRID	NTS		
GENERAL TOLERANCES (UNLESS SPECIFIED)			
ANGULAR TOL	± 2.0°	EC NO:	614537
4 PLACES	±	DRWN:	RYEH 2019/03/27
3 PLACES	±	CHK'D:	YCHENG 2019/03/27
2 PLACES	±	APPR:	YCHENG 2019/03/27
1 PLACE	±	INITIAL REVISION:	
0 PLACES	±	DRWN:	CLLI 2004/10/04
		APPR:	MHUANG 2004/10/06
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	SERIES
		C-SIZE	73100

molex			
BNC JACK, R/A RECEPTACLE 50 OHMS FILTER BNC-J/PCB/RA/BK			
PRODUCT CUSTOMER DRAWING			
DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
SD-73100-0090	PSD	001	F4
MATERIAL NUMBER	CUSTOMER	SHEET NUMBER	
SEE TABLE	GENERAL MARKET	1 OF 1	